



PK800 (v1.0) Jun 23, 2016

100% Material Declaration Data Sheet for FBG676

Average Weight : 2.7985 g

Component	Substance Description	CAS # or Description	% of component	Use in product	Component weight / substance weight (in grams)	Component % of total
Silicon Die					0.237267	8.478%
	Silicon	NA 7440-21-3	100	basis	0.237267	
Bump					0.011261	0.402%
	Tin	7440-31-5	63.00	basis	0.007094	
	Lead	7439-92-1	37.00	basis	0.004167	
Underfill					0.030000	1.072%
	Bisphenol F/ epichlorohydrin copolymer	9003-36-5	20.00	basis	0.006000	
	Phenolic resin	trade secret	15.00	basis	0.004500	
	Bisphenol A type liquid epoxy	25068-38-6	5.00	basis	0.001500	
	Amine type accelerator	trade secret	5.00	basis	0.001500	
	Silicon dioxide	60676-86-0	51.50	filler	0.015450	
	Carbon black	1333-86-4	1.00	color agent	0.000300	
Additives	trade secret	2.50	additives	0.000750		
Solder ball					0.564707	20.179%
	Tin	7440-31-5	96.50	basis	0.544942	
	Silver	7440-22-4	3.00	basis	0.016941	
	Copper	7440-50-8	0.50	basis	0.002824	
Substrate					1.955293	69.869%
	Copper	7440-50-8	36.45		0.712704	
	Tin	7440-31-5	0.91		0.017793	
	Lead	7439-92-1	0.20		0.003911	
	Silver	7440-22-4	0.02		0.000391	
	Core	N/A	48.71		0.952423	
	ABF	N/A	11.22		0.219384	
	Solder Mask	N/A	2.49		0.048687	

Revision History

Date	Version	Description of Revisions
6/23/2016	1.0	Initial Xilinx release.

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